

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.07069	100.0	1.683
Subtotal				0.07069	100	1.683
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00076	2.0	0.018
	Lead alloy	Silver (Ag)	7440-22-4	0.00095	2.5	0.0225
	Lead alloy	Lead (Pb)	7439-92-1	0.0361	95.5	0.8595
Subtotal				0.03781	100	0.9
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01019	0.03	0.2427
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01019	0.03	0.2427
	Copper alloy	Iron (Fe)	7439-89-6	0.03398	0.1	0.809
	Copper alloy	Copper (Cu)	7440-50-8	33.92425	99.84	807.7056
Subtotal				33.97861	100	809
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.20809	8.0	124
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.51012	10.0	155
	Filler	Silica fused	60676-86-0	52.08095	80.0	1,240
	Flame retardant	Metal hydroxide		1.30202	2.0	31
Subtotal				65.10118	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.67201	100.0	16
Subtotal				0.67201	100	16
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.01554	100.0	0.37
Subtotal				0.01554	100	0.37
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.12415	100.0	2.956
Subtotal				0.12415	100	2.956
Total				99.99999	100	NaN

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